

1ª Reunión Nacional

Planes Complementarios de Astrofísica y Altas Energías



Readout ASICs for single photon detectors

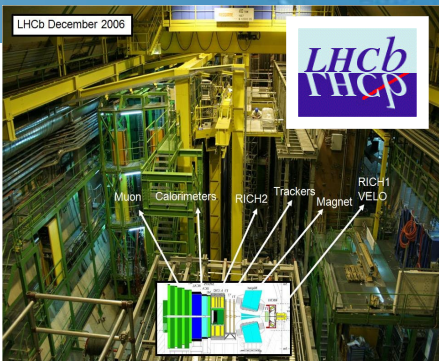


David Gascón Fora

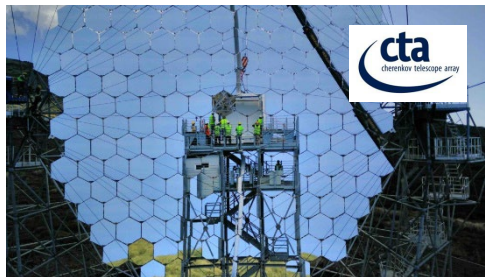
On behalf of many colleagues



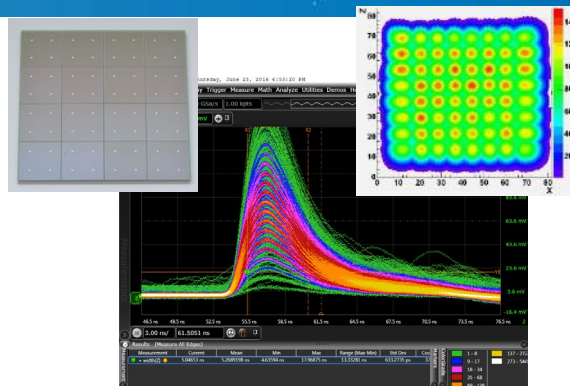
ICCUB: Photo-sensor readout in different fields



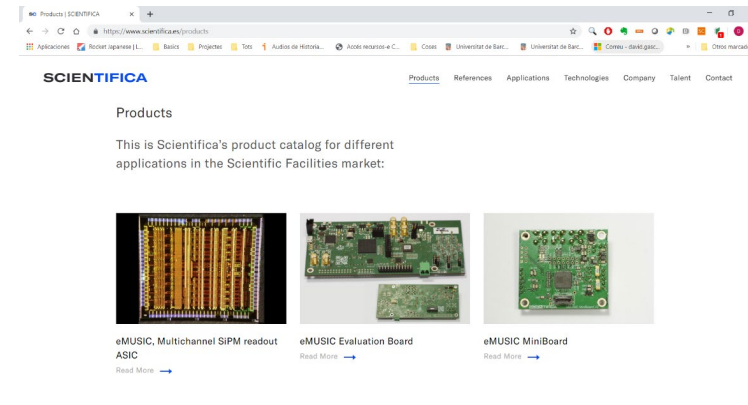
LHCb at CERN



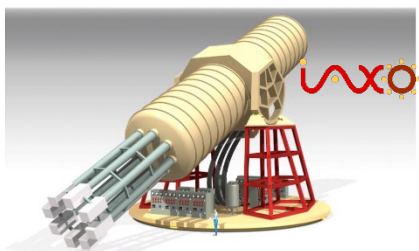
Telescope cameras



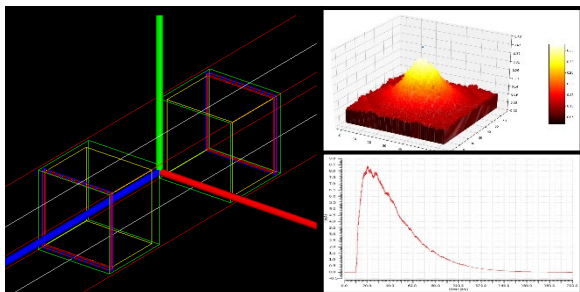
Single-Photon Sensors



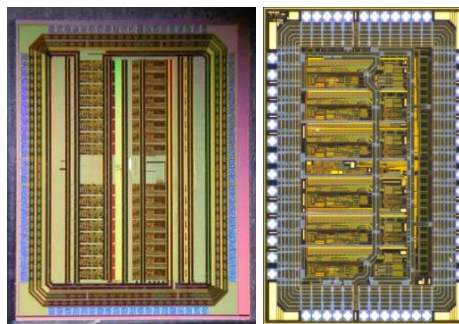
Technology Transfer



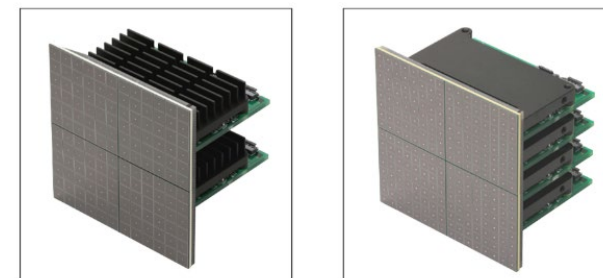
Axion and Dark Matter searches



Monte Carlo simulations



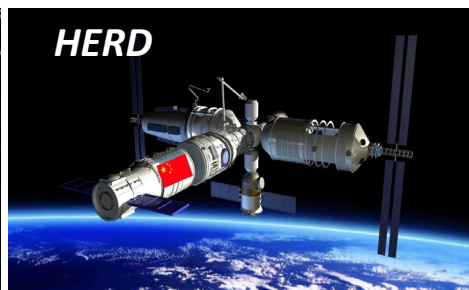
Microelectronics (Chip Design)



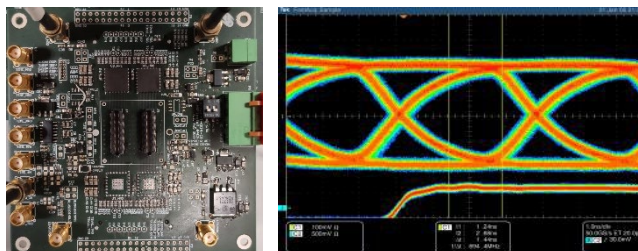
Medical Imaging (industrial collab.)



Space missions

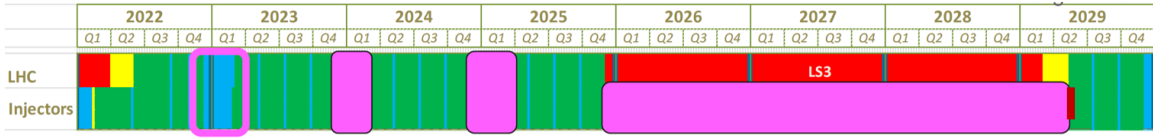


HERD



Electronics

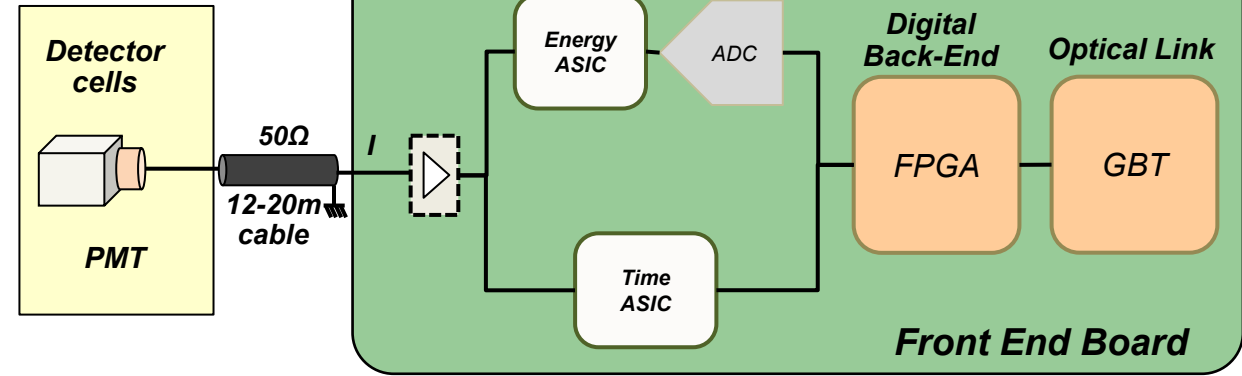
LHCb upgrade Upgrade II: PicoCal (LIA1)



YETS 22/23 YETS 23/24 EYETS 24/25 LS3 (shifted by 1 year and extended to 3 years) HL-LHC

HL-LHC: Photodetectors and FE electronics

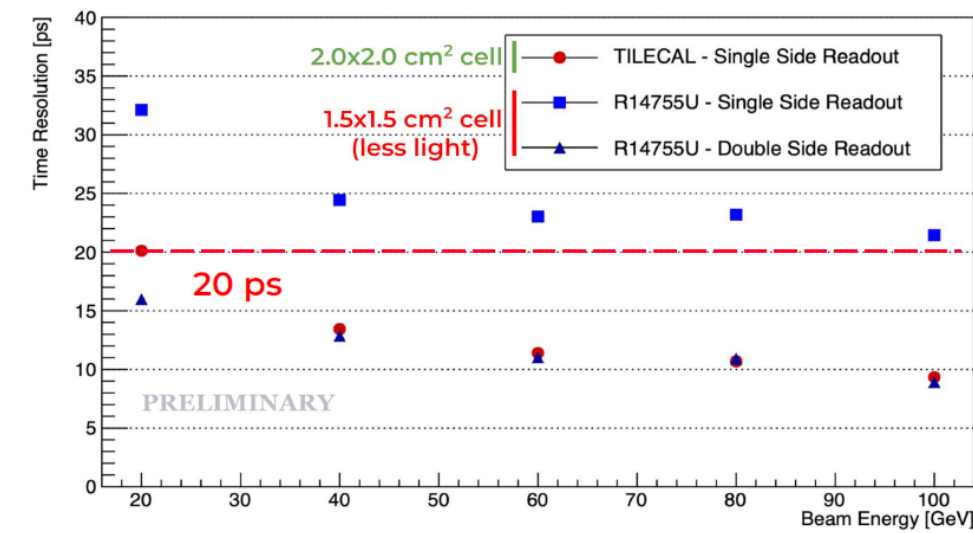
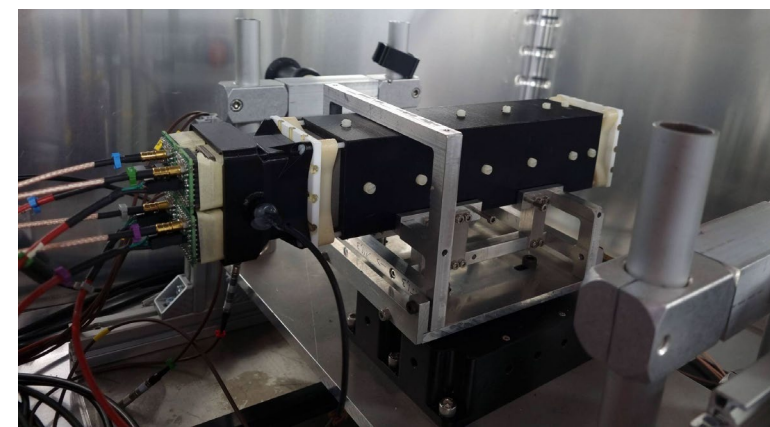
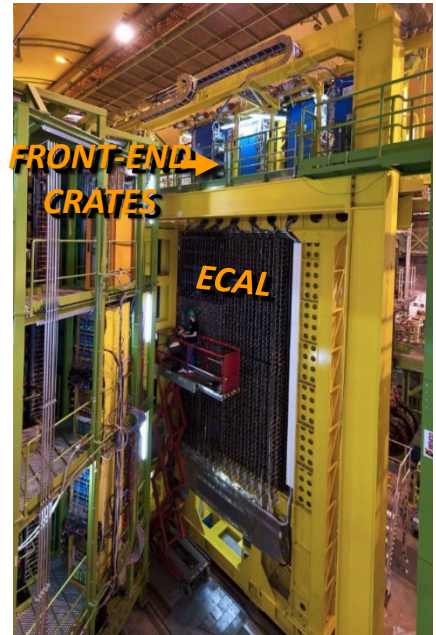
- Involved in Calorimeter FE electronics since 1999
- Responsible of current calorimeter front-end (ICECAL)
- R&D for HL-LHC: Calorimeter, RICH and Scintillating Fiber Tracker



Precise Timing is critical for HL-LHC

PicoCal Project: LS4 upgrade of LHCb calorimeter

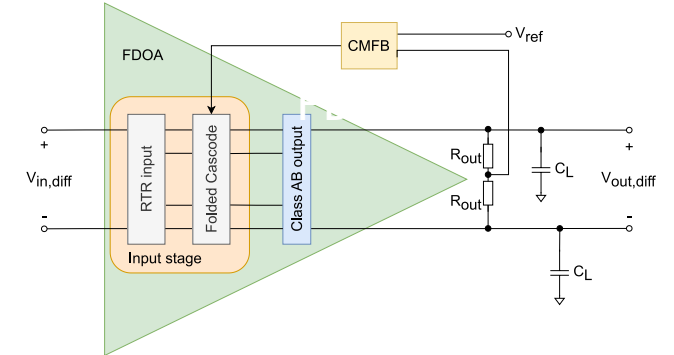
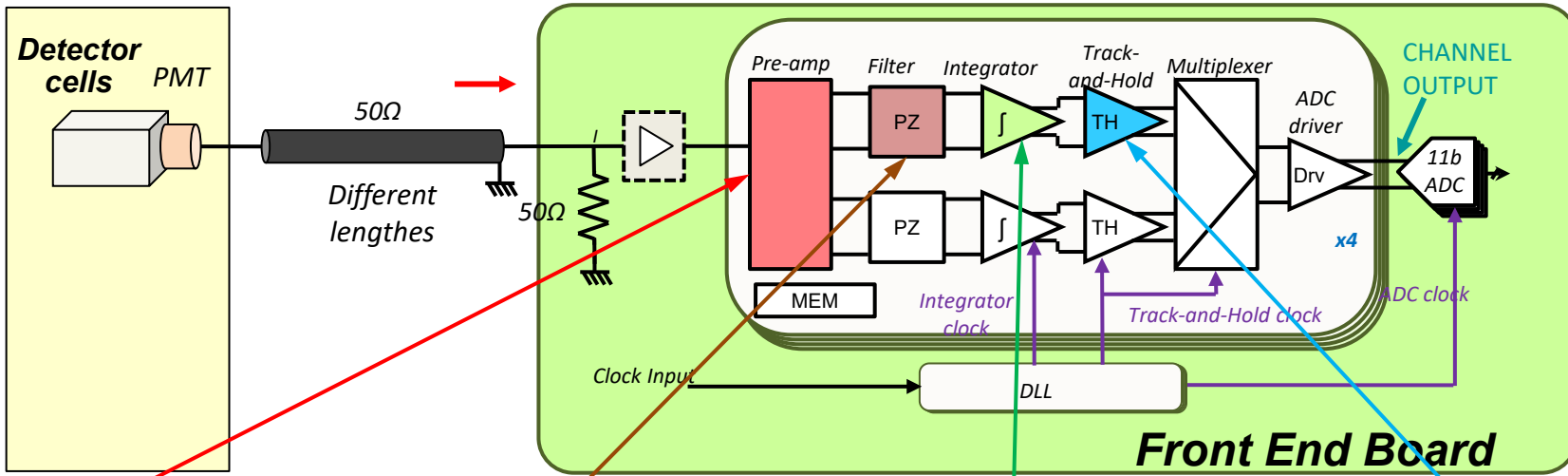
SPACAL W-Polystyrene: 10 ps @ 100 GeV
No significant degradation after 12 m cables



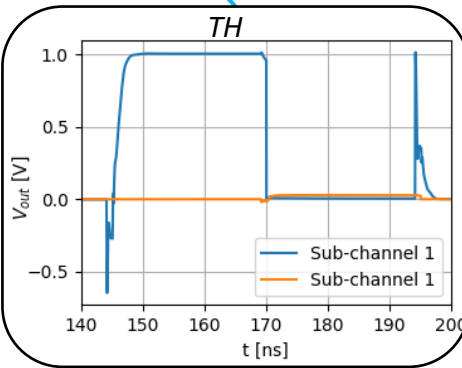
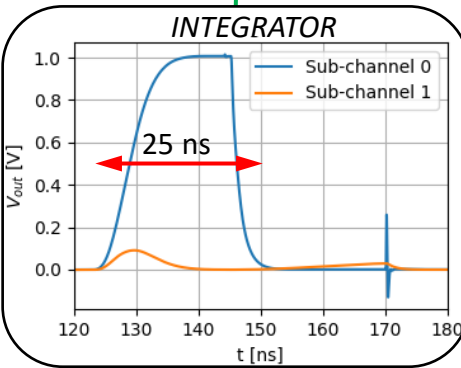
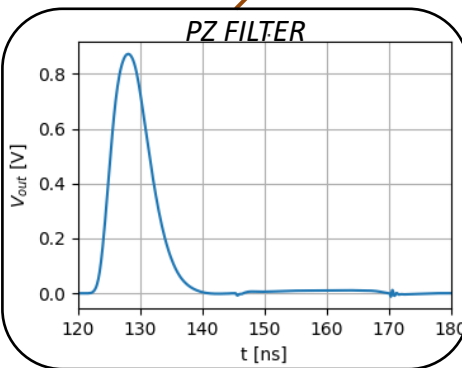
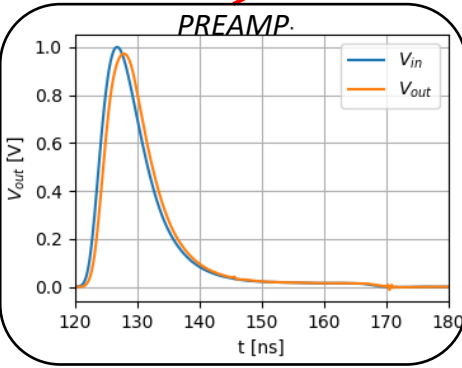
LHCb upgrade Upgrade II: PicoCal (LIA1)



- ICECAL65 chip being designed for PicoCal (ICCUB, UPC, IFIC)
 - Time-interleaved double channel scheme for integrator recovery
 - 2 gains to cover the large dynamic range



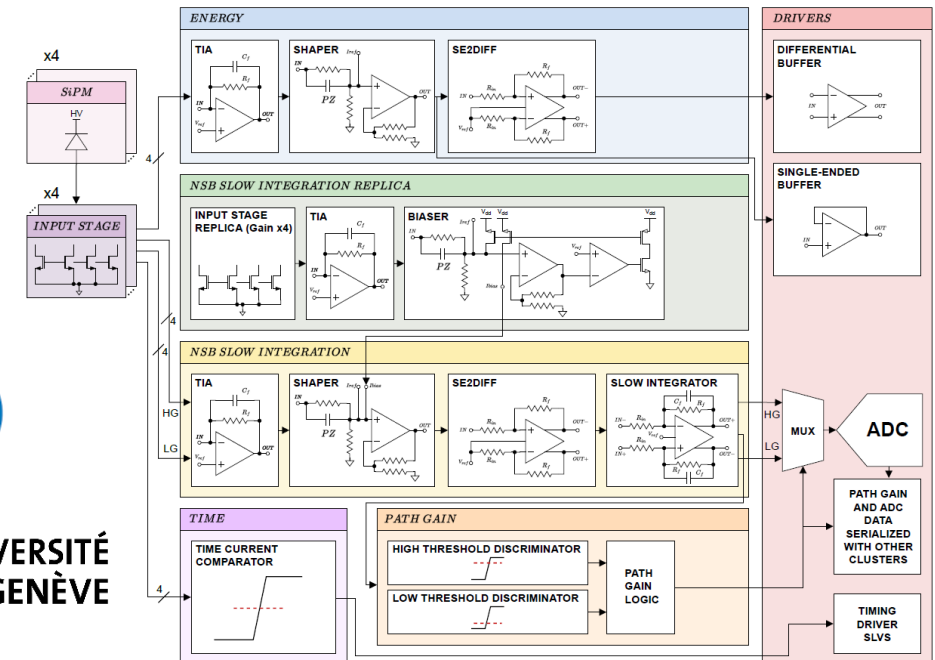
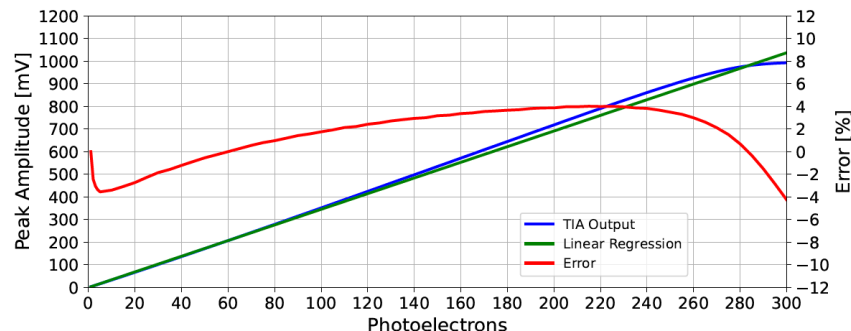
- TSMC 65nm technology
- Fully differential
- Rail-to-Rail (0-1.2 V)
- Low frequency gain > 70 dB
- GBW > 500 MHz
- PM > 65°
- SR > 0.5 V/ns
- VCM ~0.6V
- Power optimization



Cherenkov Telescope Array (LIA2)

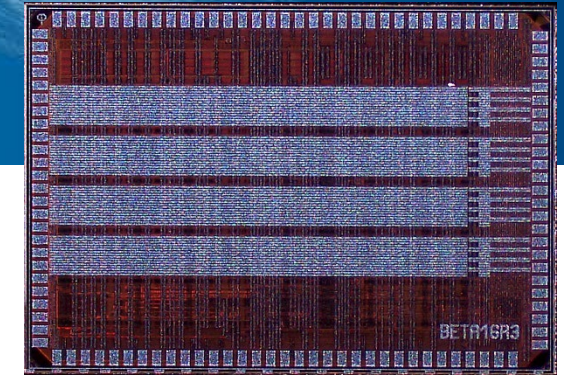


- ICCUB has developed 3 different chips with important contributions to the cameras
 - More than 100,000 chips produced to equip 15 cameras
 - Robotic system for quality control
- In LIA2 we are contributing to the advanced SiPM camera for the Large Sized Telescope
 - Preamplifier Readout Electronics for Summing SiPMs Enhanced Circuit (PRESSEC) ASIC
 - Collaboration: ICCUB, UPC and University of Geneva
 - Submission in Q1 2025
 - Energy measurement and NSB Slow Integration



HERD: BETA ASIC (LIA2)

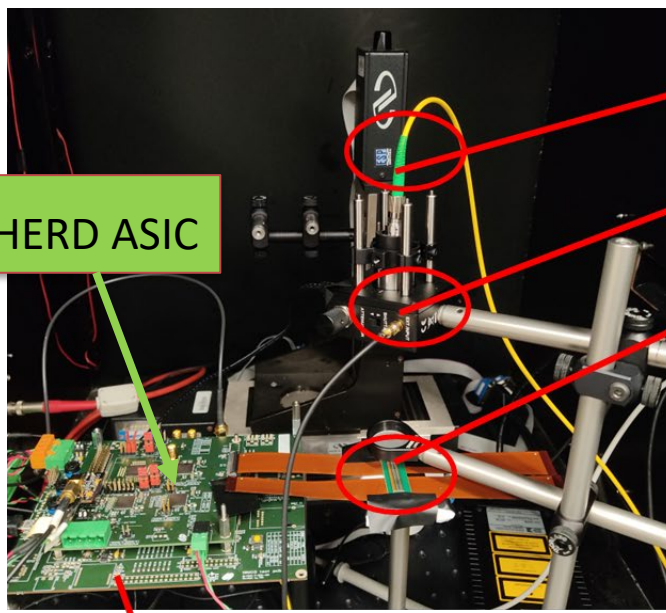
See J.Rico plenary talk



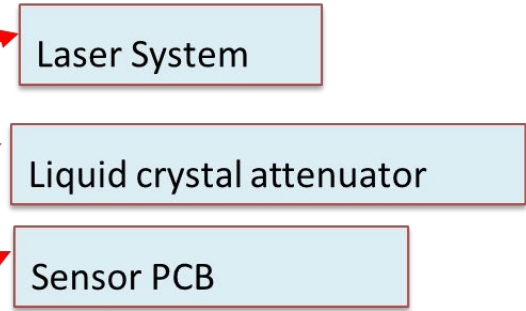
16 ch - 130 nm CMOS – 9 mm²

- ✓ Channels: 16 (PSD) or 64 (FIT)
- ✓ Event rate : 10 kHz max
- ✓ Configurable preamplifier gain: 4 bits
- ✓ Tunable shaping time: 300 ns to 1.5 us
- ✓ Trigger output: < 250 ps time resolution

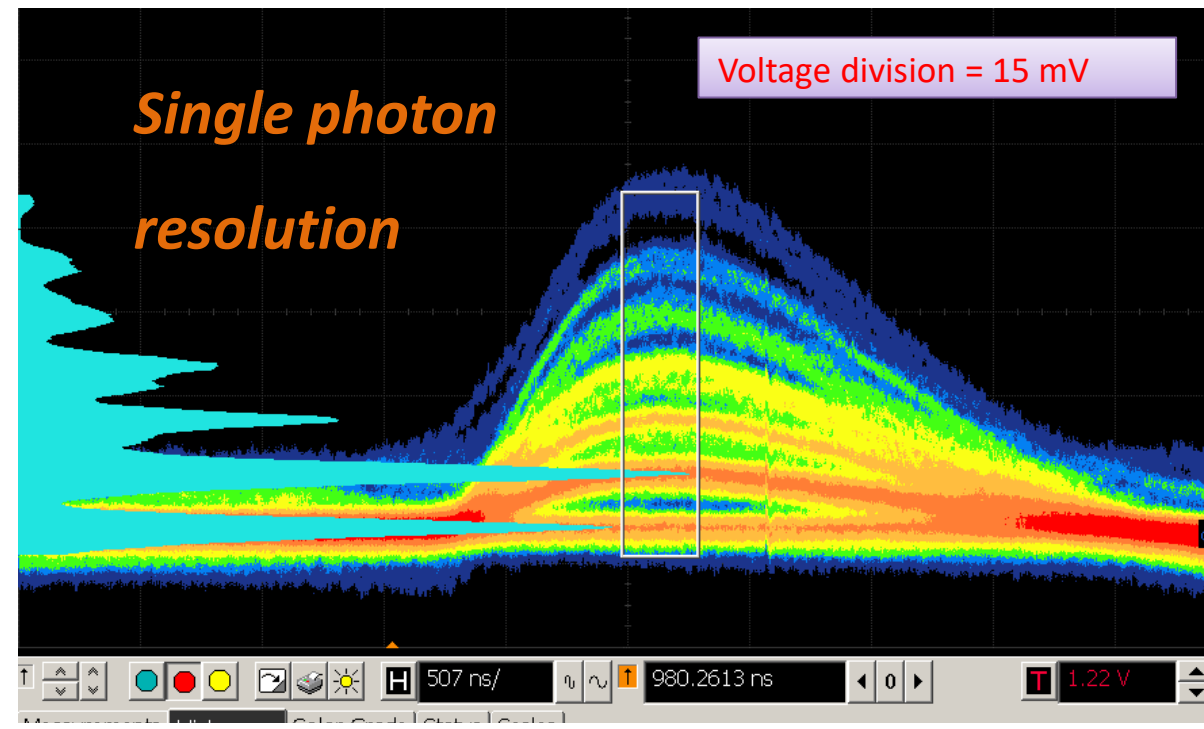
- ✓ Single photon resolution: SNR >10
- ✓ Dual path: automatic gain switching
- ✓ On chip ADC: Wilkinson 11 bit + 1bit (path sel)
- ✓ Dynamic Range : 15 bit
- ✓ Slow Digital Control : I2C
- ✓ Power Budget : <1 mW/ch



HERD ASIC



Digital PCB (FPGA)

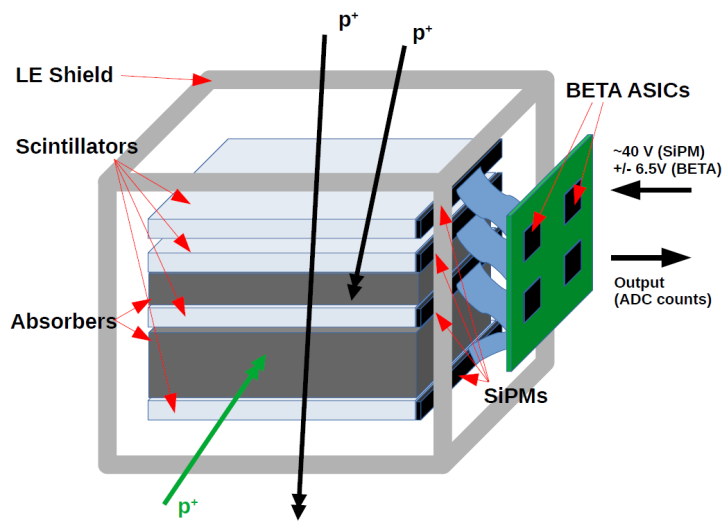


Sanmukh, A.. et al. Low-power SiPM readout BETA ASIC for space applications. NUCL SCI TECH 35, 59 (2024). <https://doi.org/10.1007/s41365-024-01419-z>

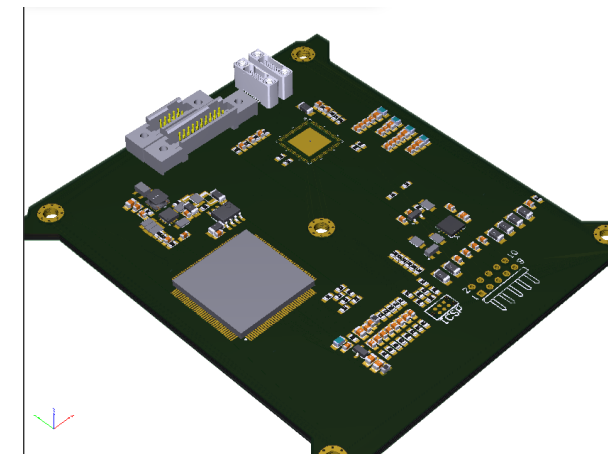
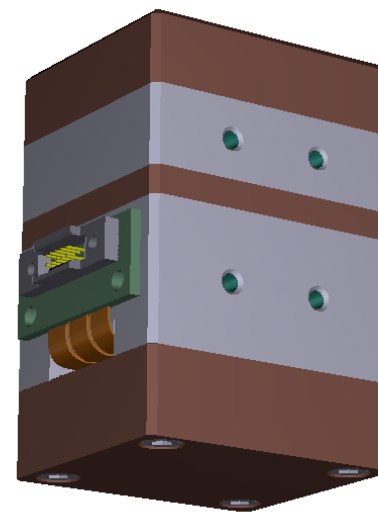
Other space instruments based on BETA ASIC

See M. Nofrarias plenary talk

- A radiation monitor based on BETA-ASIC is being developed for LISA mission
 - IEEC project (LIA3)



- Plastic scintillators + SiPMs for particle detection
 - High-density absorbers for achieving some energy resolution
 - Shield for blocking low-energy particles (as in LPF-RM)
 - SiPM readout with the BETA ASIC
- Can read up to 16/64 SiPMs per chip.
Digital output with a few mW/channel



- Other missions and CubeSat projects are considering BETA chip
 - APT/ADAPT, GENE0-02 et al

R&D: Towards a new vertically integrated sensor

- *FastIC collaboration: ICCUB (Univ. Barcelona) and CERN microelectronics section*
 - <https://ep-news.web.cern.ch/content/fastic-and-fasticpix-developments>
 - FastIC chip family: FastIC, FastIC+ and FastRICH
 - ATTRACT project to explore new sensor architecture

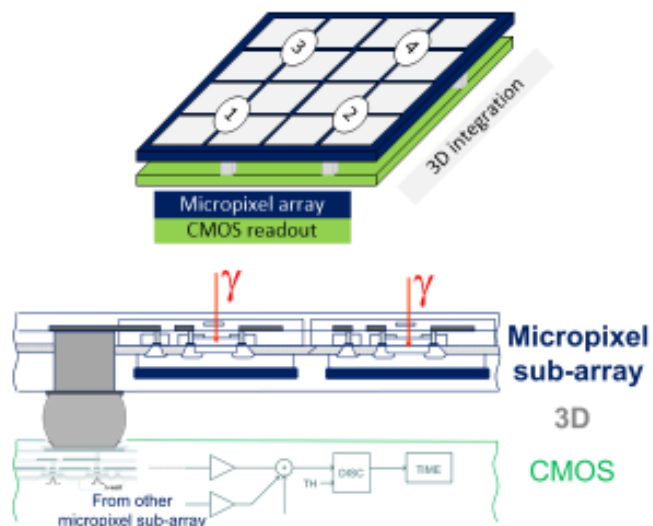
DEVELOPING BREAKTHROUGH TECHNOLOGIES FOR SCIENCE AND SOCIETY



*J. Mauricio, R. Manera S. Gomez,
A. Sanuy, D. Gascon et al @ ICCUB
J. M. Fernandez-Tenllado, M. Campbell,
R. Ballabriga et al. @ CERN*

FastICPix: Integrated Signal Processing for a New Generation of Active Hybrid Single Photon Sensors with Picosecond Time Resolution

The Idea is to combine actively the signal of small micropixel sub-arrays based on the fastest single photon sensor technologies with ultrafast readout electronics using 3D integration.



Linked to DRD4 and DRD7

• Applications:

- Fundamental science
- Medical Imaging
- Quantum communications
- ToF detectors

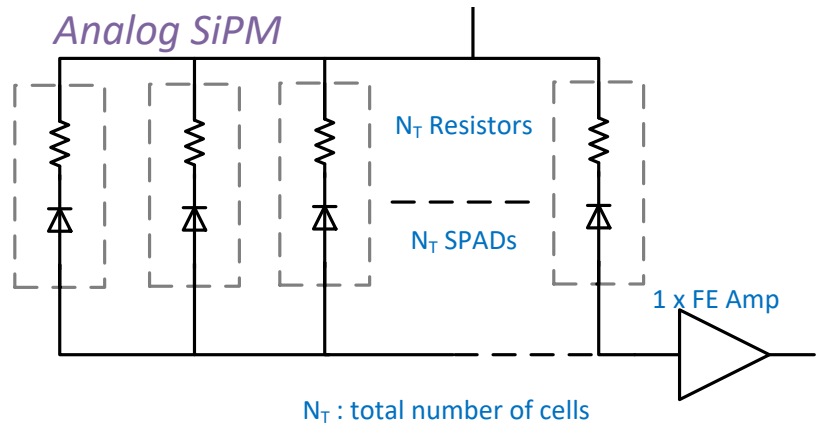


R&D: Our approach to solid state single photon sensor

• FastICpix: try to exploit optimal segmentation

- Optimization for a given *power budget* !
- Investigation of new circuit topologies
- 3D integration

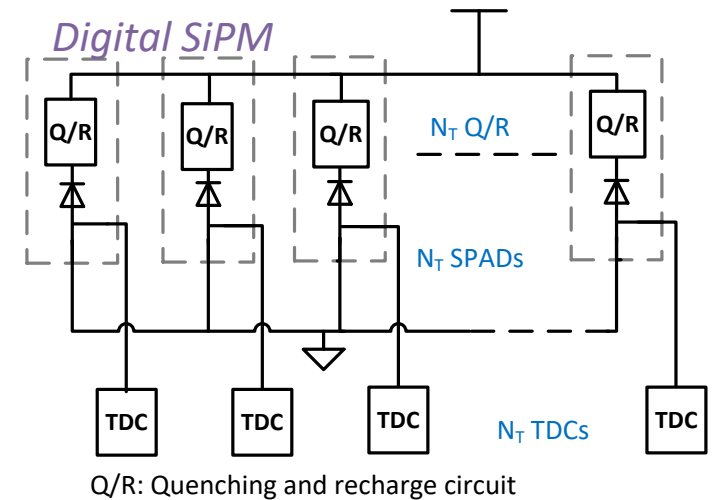
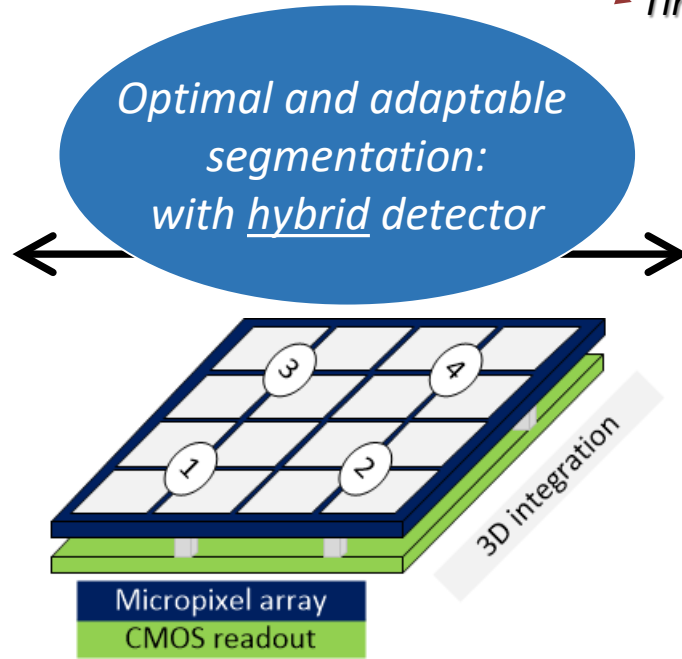
- *Electronic noise jitter < 1 ps for next generation of detectors based on prompt light*
- *Time tagging of first(s) photons*



- Pros**
- Simplicity
 - High Fill Factor (PDE)

- Cons**
- Large capacitance degrades timing
 - Xtalk degrades timing

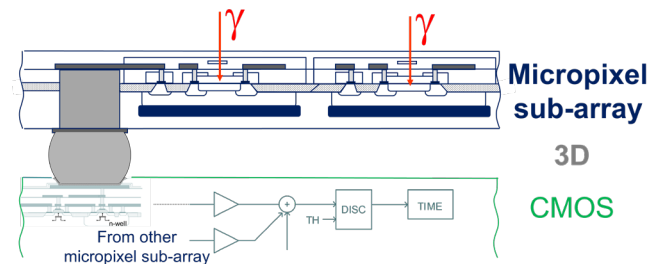
No segmentation



- Pros**
- Individual photon timing available

- Cons**
- Complexity (cost and power)
 - Fill factor degradation
 - Xtalk degrades timing

Maximum segmentation

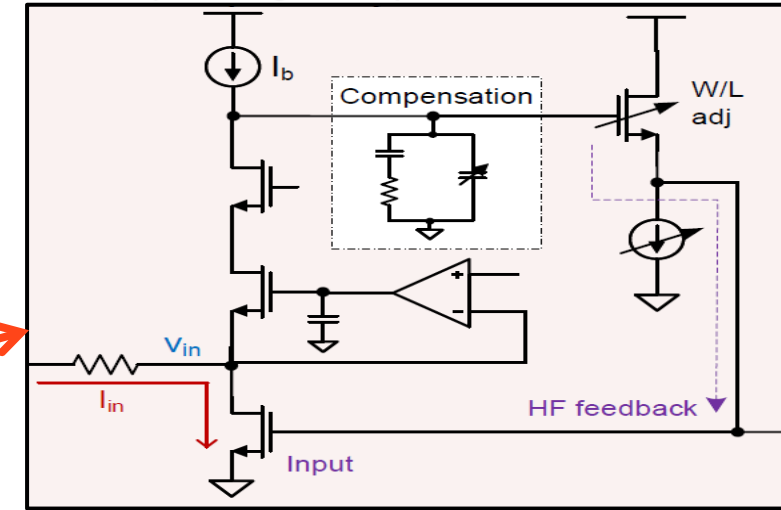


FastIC architecture

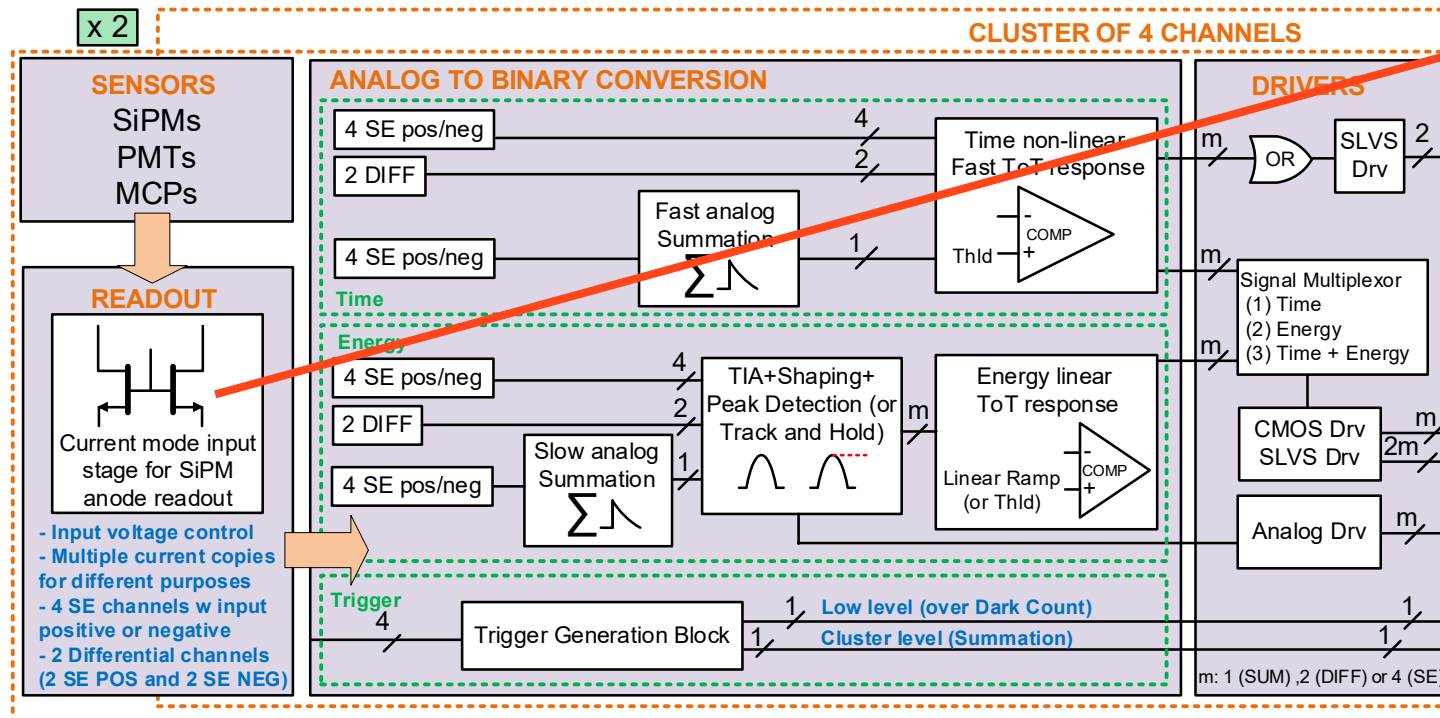
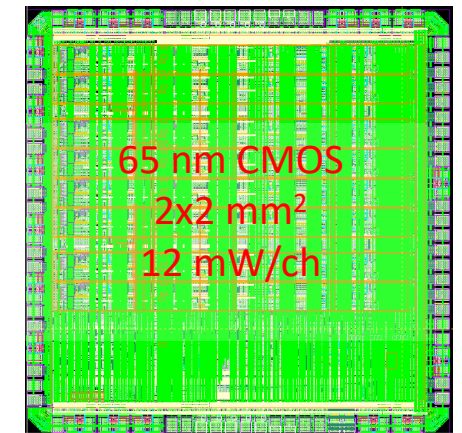
FASTIC current mode 8ch ASIC.

- Multipurpose: particle physics, medical imaging, ToF detectors
 - Fast current mode input stage
 - Current mode comparator for timing
- Compatible with SiPMs, PMTs, MCPs
- Designed to cope with capacitance from few pF to nF
- Large dynamic range: single photon to 1000s

Input stage "amplifier" < 3 mW/ch

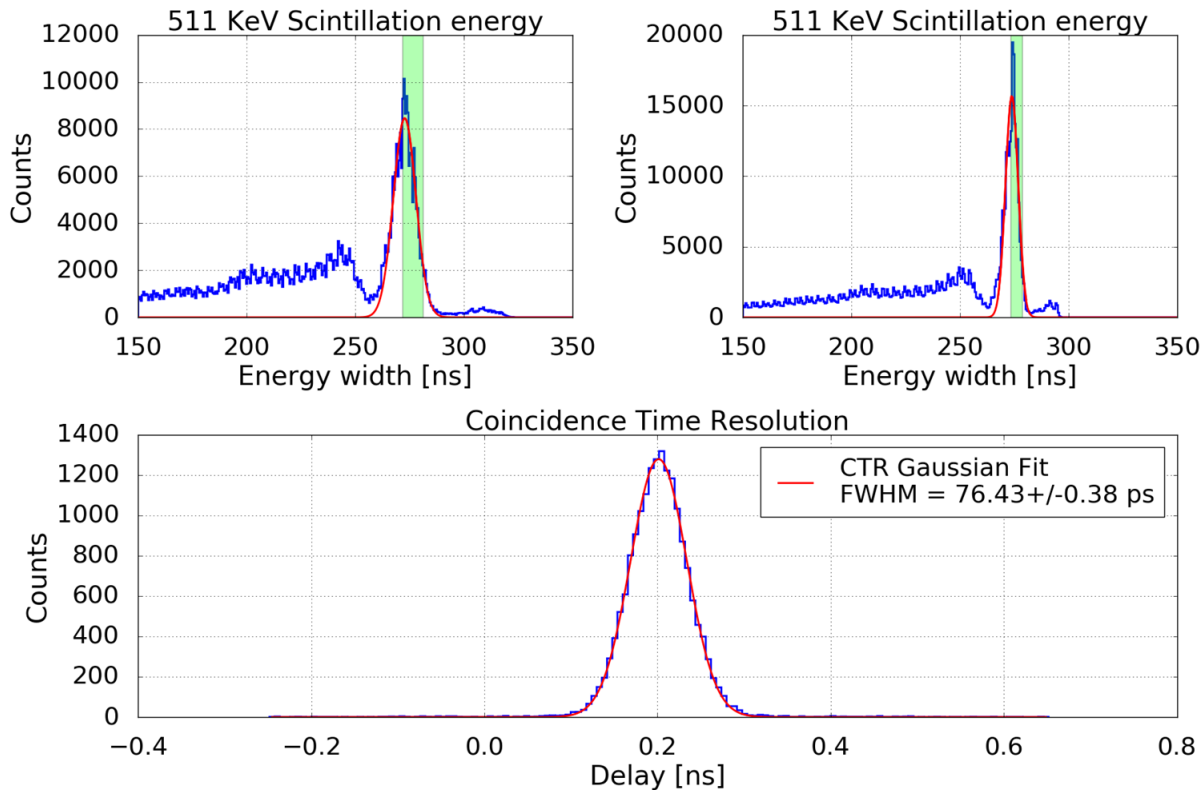


Based on HRFlexToT ASIC



- Input voltage control
- Multiple current copies for different purposes
- 4 SE channels w input positive or negative
- 2 Differential channels (2 SE POS and 2 SE NEG)

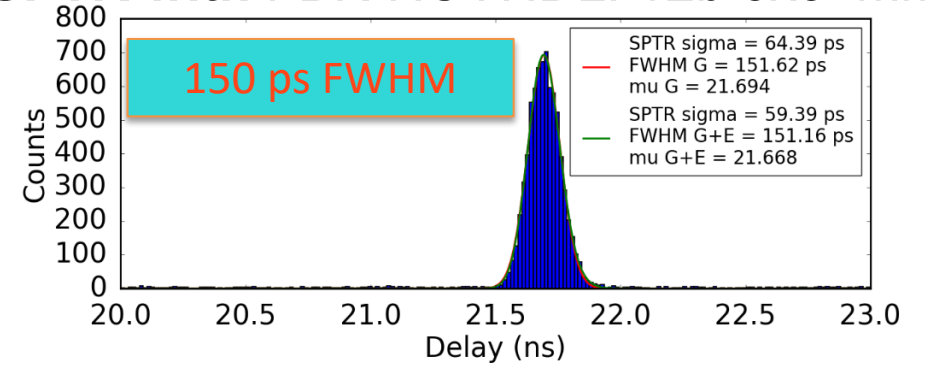
- **Sensor:** FBK-NUVHDLFv2b 3x3 mm², 40 pixel pitch.
- **Crystal:** LSO:Ce Ca 0.2% of 2x2x3 mm³.



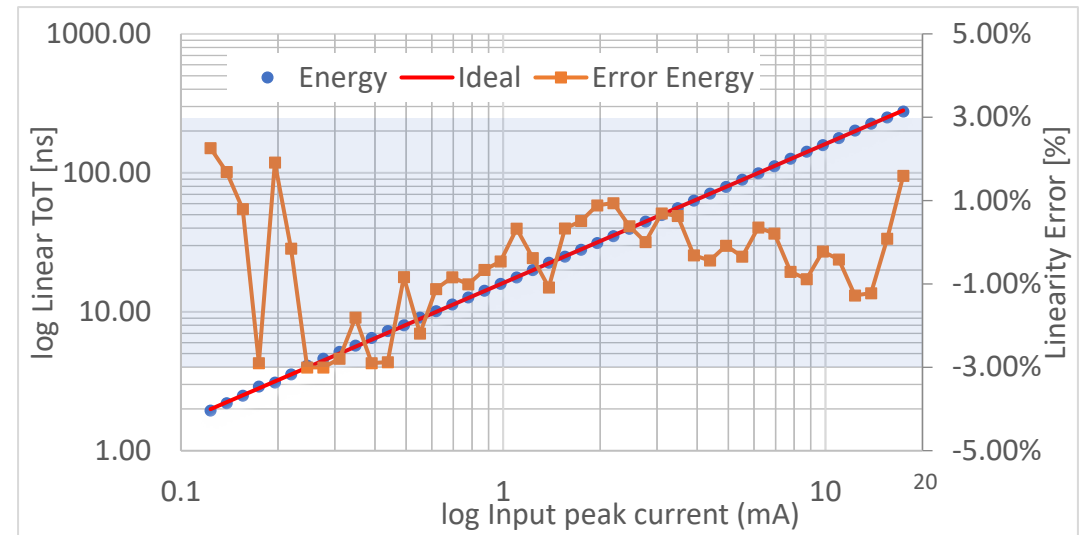
FWHM = 76 ps

Input "amplifier" < 3 mW/ch
Complete signal processing < 12 mW/ch

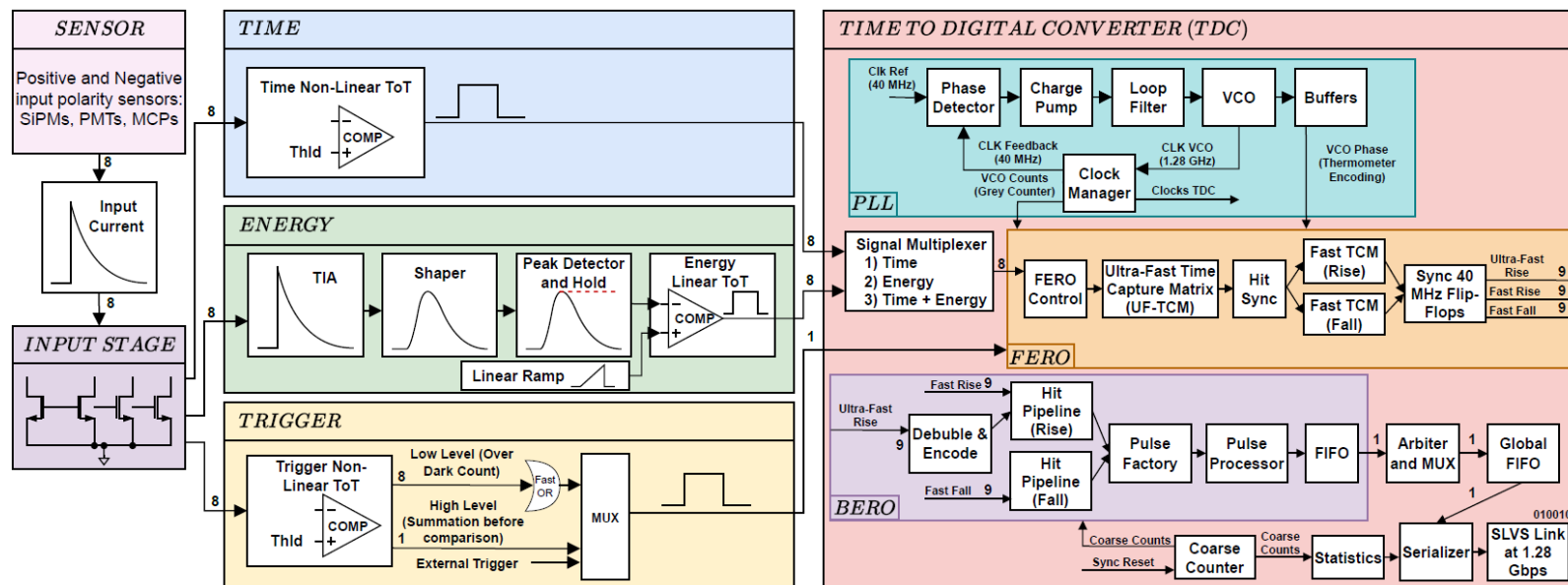
- **SPTR with FBK-NUVHDLFv2b 3x3 mm²**



- **Linearity error is below 3%**



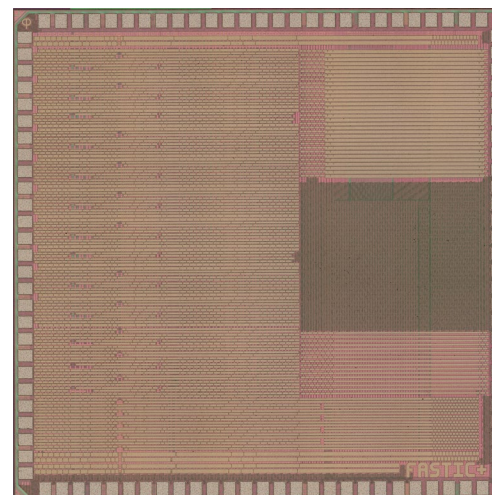
FastIC+ status



- A 25 ps time bin TDC is added to FastIC

- Back from foundry few weeks ago

- Dimension: 3x3 mm²
- Technology: TSMC 65 LP
- Metal stack: 9M + AP
- Quantity: 10 units (QFN64)
 - For internal use only
 - Standard package will be QFN88
- **Very preliminary measurements!!!**
 - **THE CHIP IS MEASURED IN A SOCKET (INDUCTANCES)**

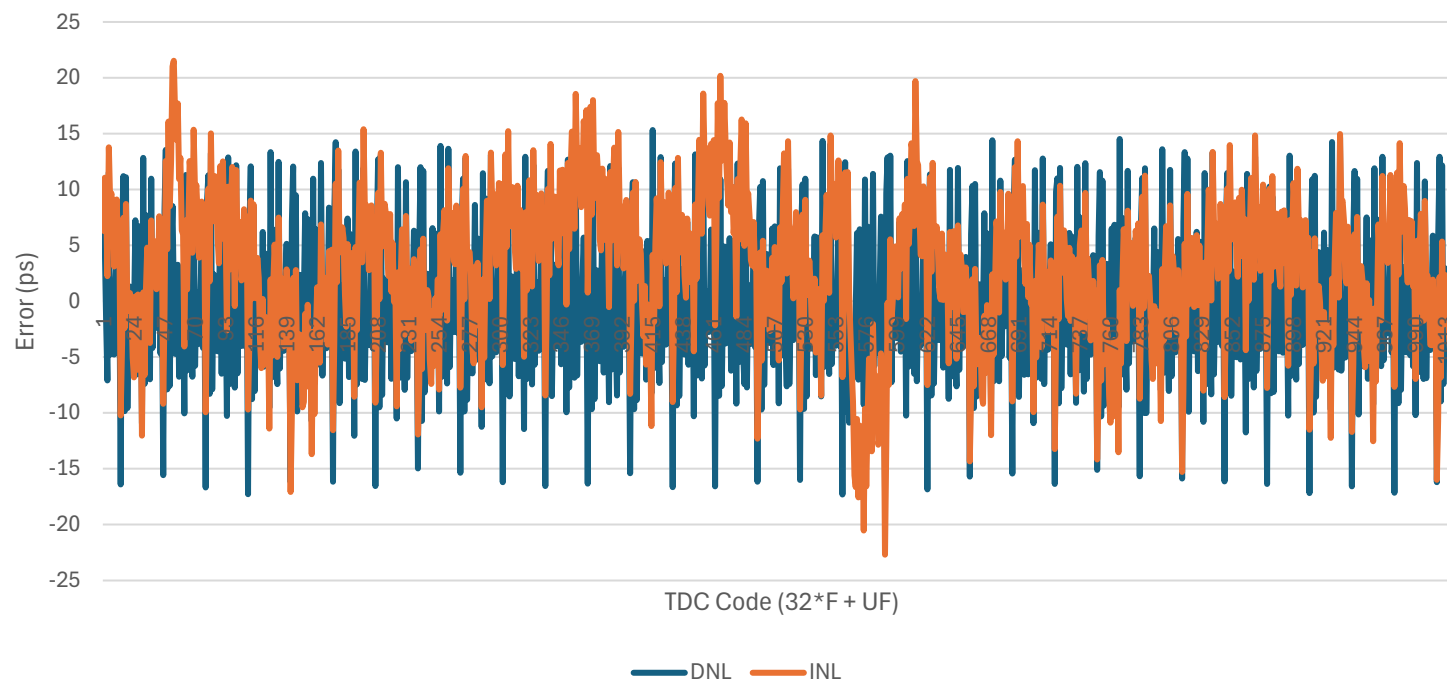


FastIC+ status



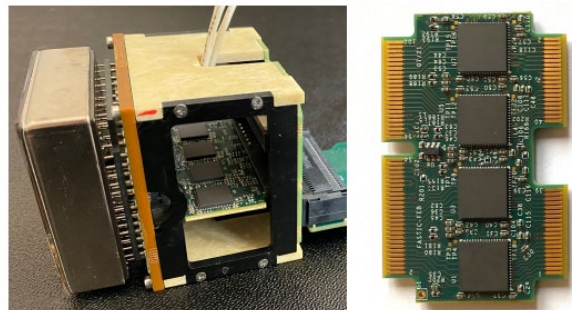
- **FastIC+ is alive and kicking 😊**
 - QFN88 packaging has been already asked
- **Quite promising TDC performance:**
 - Jitter < 12 ps
 - DNL < 6 ps
 - INL < ± 22 ps
 - TDC Power Consum.: 24.6 mW
 - ~ 3 mW/ch
- **No big issues have been identified for the moment**
- **Very preliminary:**
 - The chip has been tested in a socket in a sub-optimal (compatible) package.
 - Not tested in an optical setup yet.
 - No fine parameter tuning to obtain the best timing resolution.

TDC Trigger Channel DNL & INL Error (TDC Code Density Test)



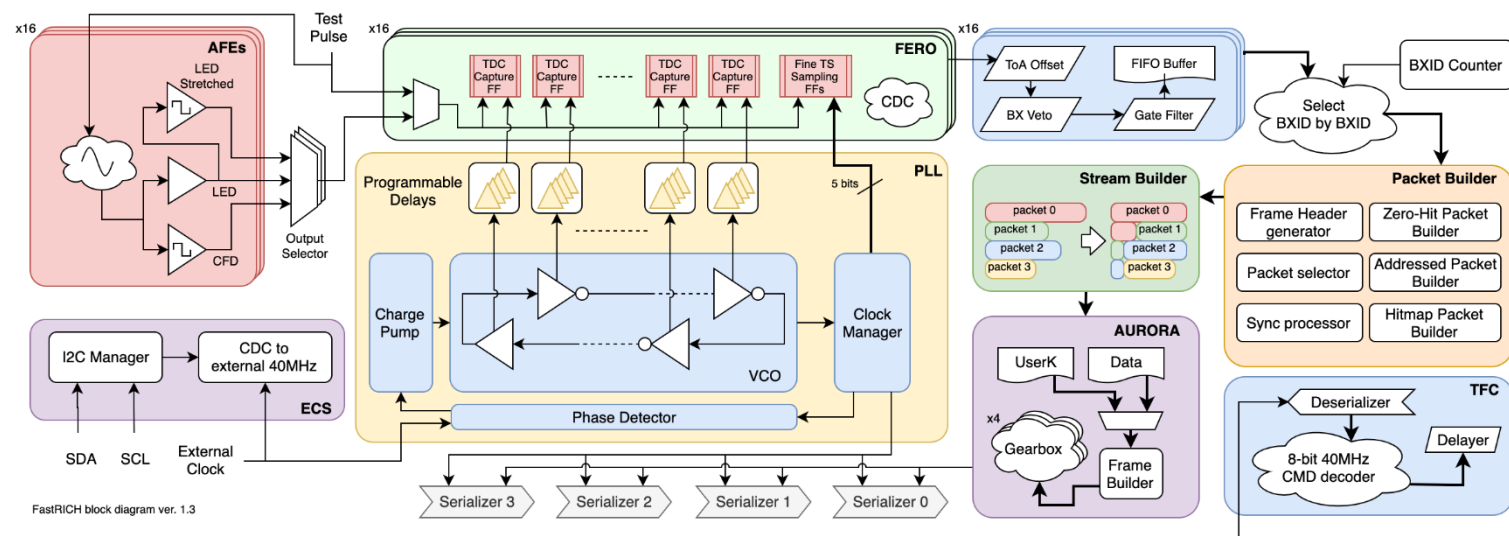
Spin-back from R&D: FastRICH (LIA1)

- FastIC is used in LHCb RICH upgrade test beams
 - Readout and DAQ electronics developed by LHCb RICH groups



See: F. Keizer, “A novel fast-timing readout chain for LHCb RICH LS3 and prototype beam tests”, NIMA, Vol. 1055, 2023, <https://doi.org/10.1016/j.nima.2023.168475>.

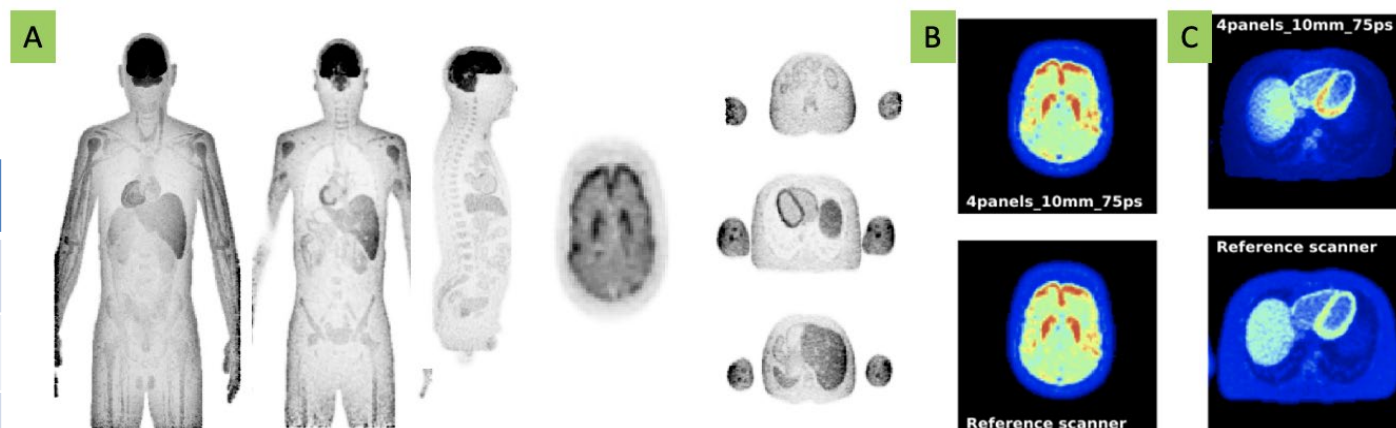
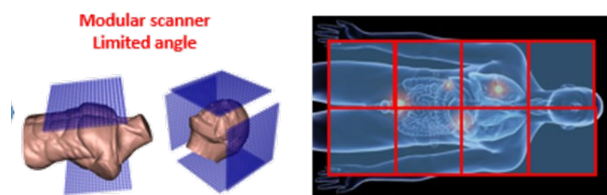
- FastRICH: a dedicated 16 ch ASIC for RICH upgrade in LS3
 - Optimized for single photon detection
 - Compatible with PMTs and SiPMs
 - CFD to deal with time walk @ high rates
 - Nearly the same PLL and TDC blocks integrated in FastIC+
 - Technology: TSMC 65 LP
 - Schedule: submission during 2024



More information on: <https://fastrich.docs.cern.ch/>

Tech Transfer: Towards a new ToF-PET scanner concept

- The **PETVision** Project was approved! Call: **Horizon EIC 2022 Pathfinder-open**.
 - 5-year project started in September 2023
- The aim of PetVision is to leverage on vertical integration techniques to build a modular ToF-PET scanner, with next-generation performance and affordable cost.

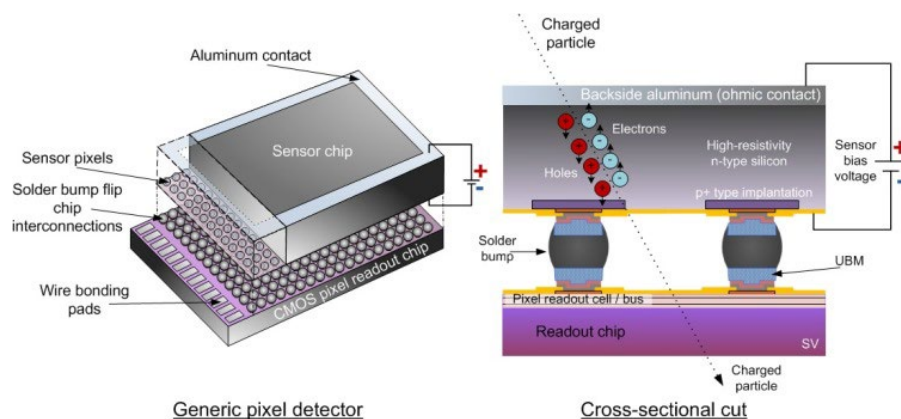


Simulation of the capability of the proposed planar TOF PET imager:
 Reconstructed Image (3mm slices) of an XCAT digital phantom acquired by two $120 \times 60 \text{cm}^2$ panel detectors (above and below the patient) assuming 100 ps TOF resolution and 10 mm scintillator thickness (A) and with small 4 panel system used to image head (B) and torso (C)

Partner	PI	Country
JSI	Rok Pestotnik	SI
FBK	Alberto Gola	IT
ICCUB	David Gascon	ES
Oncovision	Jorge Alamo	ES
CSIC	Jose Maria Bennloch	ES
TUM-MED	Wolfgang Weber	DE
Yale	Georges El Fakhri	USA

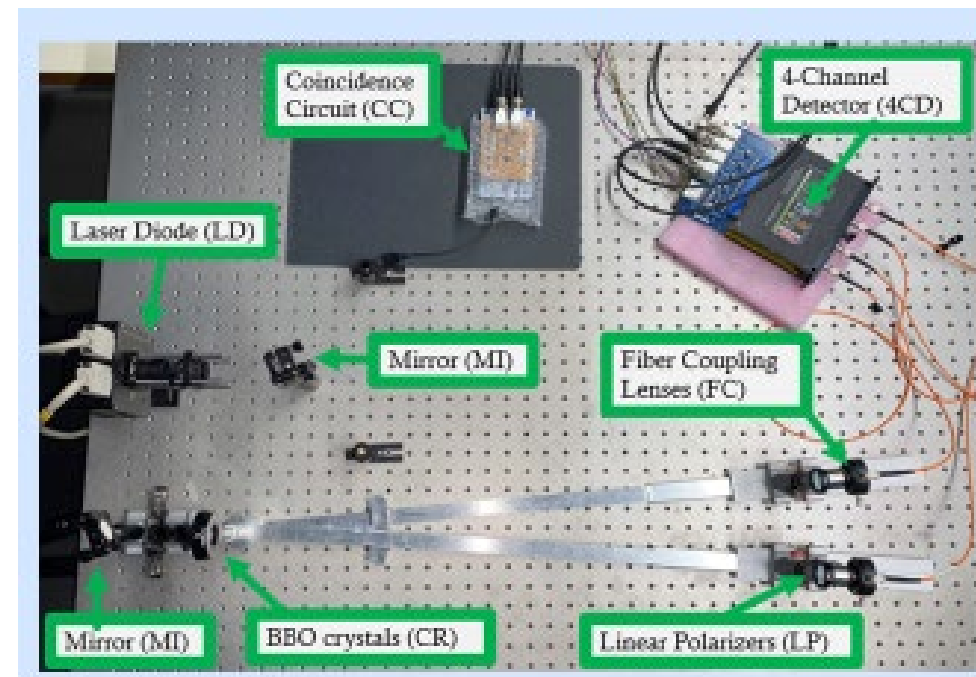
New vertical integration facilities

- Different facilities for electrical and optical characterization
 - Picosecond laser, micro-positioning systems, GS/s acquisition, thermal chamber, etc
- New infrastructures for vertical integration: sensor and integrated readout
 - Under preparation
 - Microprobe automatic station
 - Flip-chip and bump bonding
 - Clean room for integration and test



Summary

- Try to define a coherent technology development plan with impact in different areas (LIAs 1,2 and 3 for the moment)
- Contributions to experiments, missions and upgrades
- Seed activities for ECFA's DRD program
 - Involved in DRD4, DRD6 and DRD7
 - Leading Fast Timing and Readout Electronics Task in DRD4.1
- Technology Transfer of our technology
 - Impact on medical imaging
 - New activity on quantum communications



Thanks a lot for your attention !!!

<http://icc.ub.edu/technology>

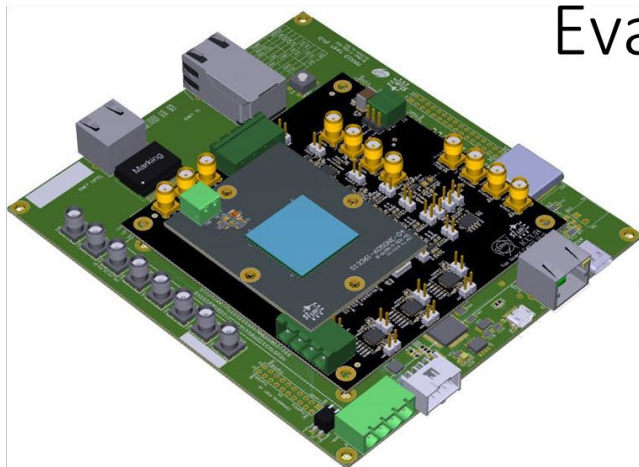
Thanks a lot for materials and contributions to our colleagues !!



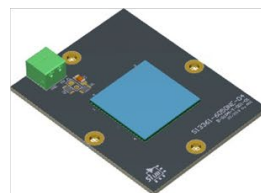
dgascon@fqa.ub.edu

FastIC support and evaluation boards

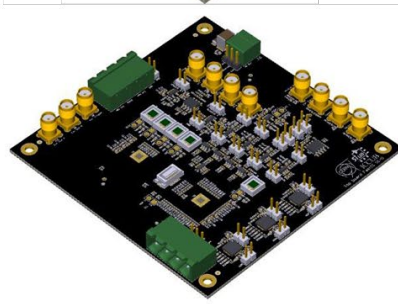
Evaluation system



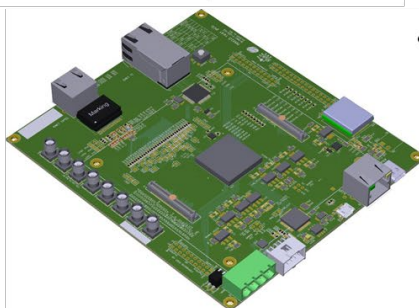
- Aims of the evaluation system:
 - Basic operational test & debug ASIC functionalities
 - Initial electrical characterization and linearity analysis.
 - Initial benchmark i.e. evaluate the FastIC chip by comparison
 - With respect previous designs (NINO, HRFlexTOT)
 - Using reference SiPM sensor:
 - Hamamatsu S13360-3050CS
 - FBK NUV-HD
 - Interface with other sensor based on adaptor board
 - Signal acquisition:
 - FPGA-based TDC (45ps time bin)
 - Differential sLVS link to external system



- Custom sensor board



- FastIC generic board
 - 2 FastICs on QFN64 (16 channels)
 - Reference SiPM sensors included
 - The board can be used stand alone



- FPGA board
 - FPGA board for slow control, acquisition and additional biasing.
 - Multichannel TDC is implemented in the FPGA (45ps time bin)

• Documentation, software and support available at

- <https://icc-ub.gitlab.io/instrumentation/documentation/index.html?page=fastic>
- Contact: fastic_support@fqa.ub.edu

Quantum Communications Group

Team

Bruno Julia Díaz - Dept. Quantum Physics and Astrophysics and ICCUB

José María Gómez Cama - Dept. of Biomedical Engineering and ICCUB

Martí Duocastella - Dept. of Applied Physics

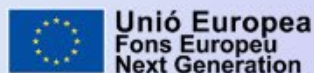
Raul Lahoz Sanz - PhD student

Lidia Lozano Martín - PhD student

Adrià Brú i Cortés - Undergrad Physics and Electronics engineering



<https://quantumcomms.fqa.ub.edu/>



VI. Quantum technologies

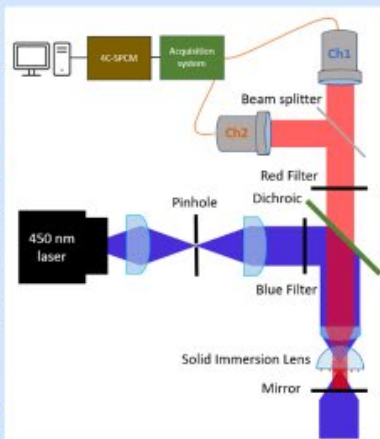
WP1) Enhanced production of single and entangled photon from quantum dots
WP2) Characterization of their entanglement properties by means of a versatile Bell test.

Current funding from Planes Complementarios de Comunicaciones Cuánticas (until Sep 2025)

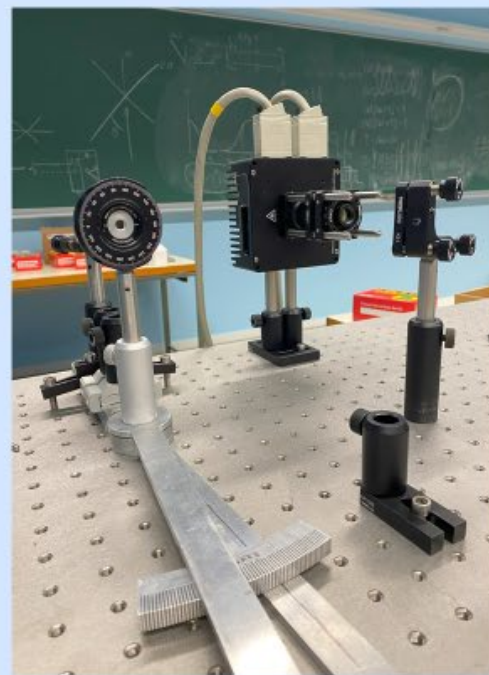


 <https://quantumcomms.fqa.ub.edu/>

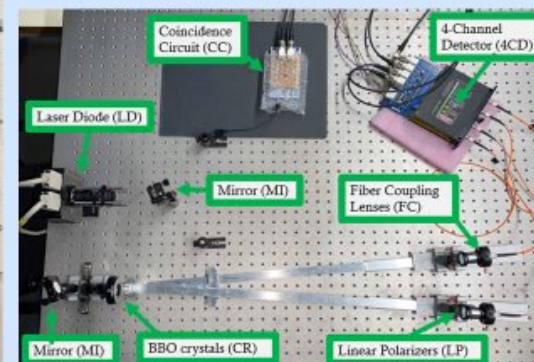
VI. Quantum technologies



Photon antibunching experiment

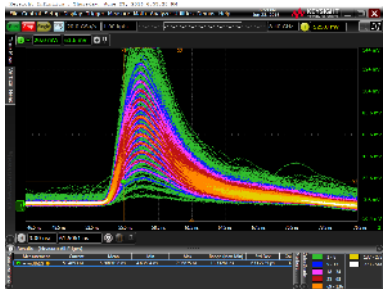
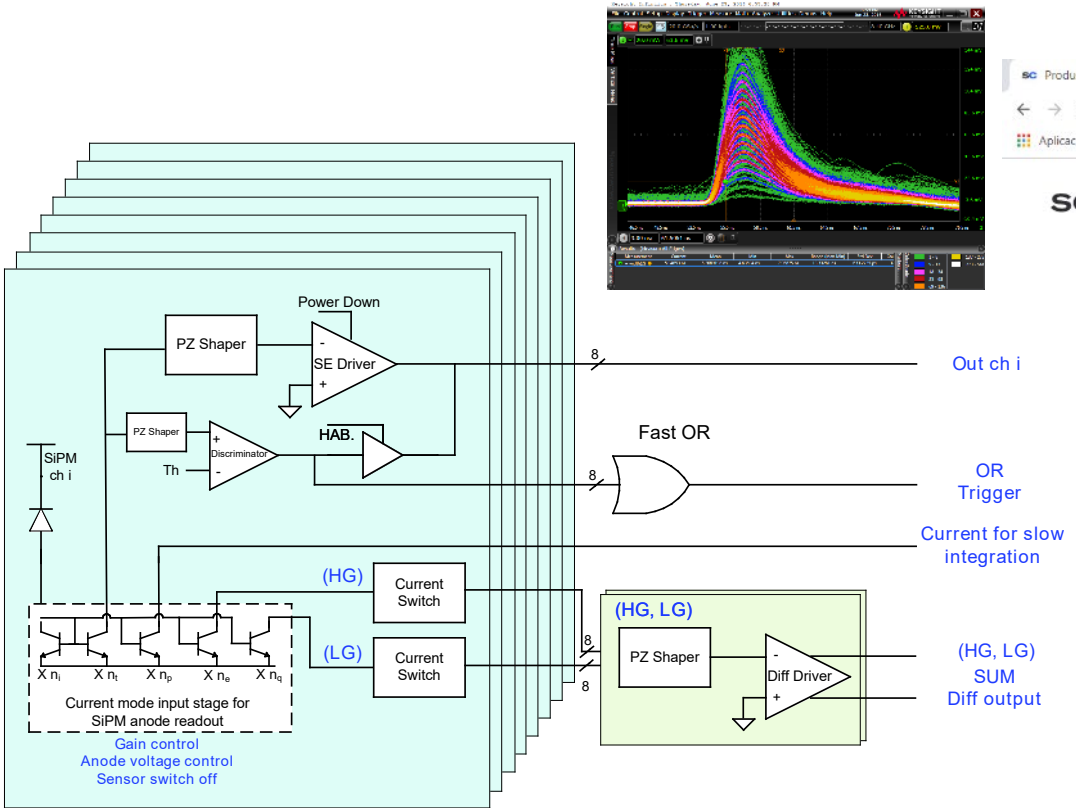


Bell test for entangled photons



VII. Technology transfer

- Technology protected by patent and commercialized
 - Licensed to Scientifica international
 - Chip and evaluation boards are commercially available
 - Part of wider collaboration agreement



Products | SCIENTIFICA

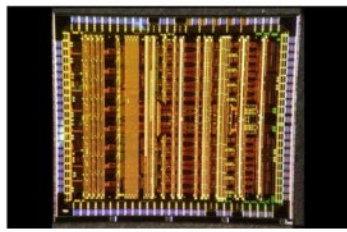
https://www.scientifica.es/products

SCIENTIFICA

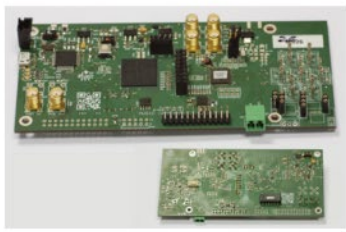
Products References Applications Technologies Company Talent Contact

Products


This is Scientifica's product catalog for different applications in the Scientific Facilities market:



eMUSIC, Multichannel SiPM readout ASIC
[Read More](#)



eMUSIC Evaluation Board
[Read More](#)



eMUSIC MiniBoard
[Read More](#)

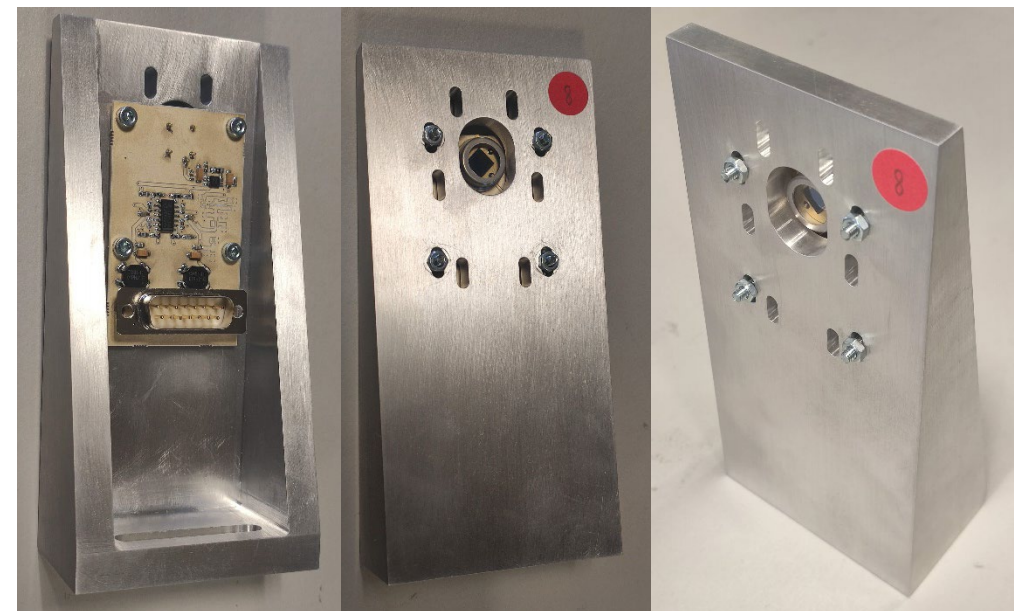
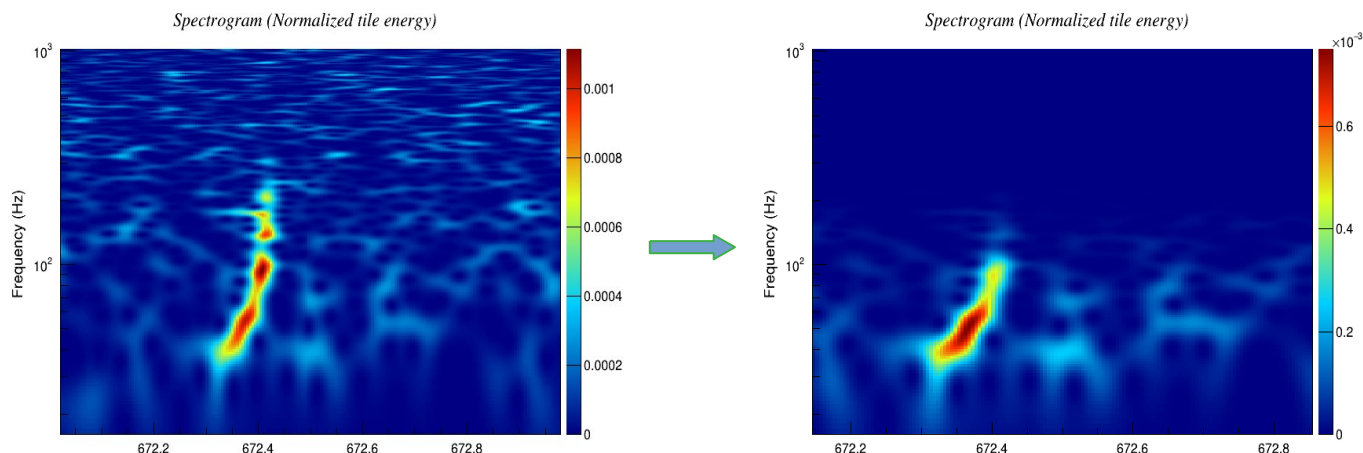
Software/Computing + Instrumentation: Virgo



- ICCUB is full member of Virgo since July 2019
 - Now **11 members**, will add 3 this year. Contributions on: **Computing, Instrumentation, Data analysis, Science, Outreach**
- **Computing:**
 - Quite in stand-by (our expert left, now waiting for new manpower to arrive: COVID + India...)
 - So far: Computing Model revision, migration to modern software tools (CMake + Conda, Git)
 - Soon: Low-latency end-to-end test facility and off-site porting, support to pipelines development, data handling improvements...

(see GW presentation by R. Emparan/M. Gieles)

- **Instrumentation:**
 - Quantum Noise Reduction:
2D Position Sensitive Devices + electronics + mechanics + test → (to be operated in **vacuum** → outgassing tests)
- **Data analysis:**
 - rROF-based **de-noising** algorithm integrated in the **Bursts** (cWB) pipeline



II. Activities in instrumentation

Part of the *ICCUB technology unit* (TU has 2 sections: instrumentation/electronics and software/data processing)

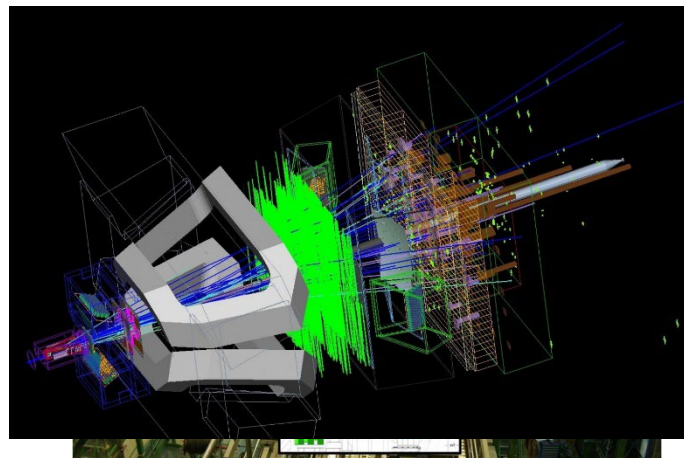
Enabling key contributions on instrumentation to ICCUB to *high impact collaborations*:

- Particle physics: LHCb, IAXO
- Ground instruments: CTA, VIRGO
- Space missions: LISA (ESA-L3), HERD

Close coordination other ICCUB research groups and Electronics Department (Solar Orbiter, Ariel and others)

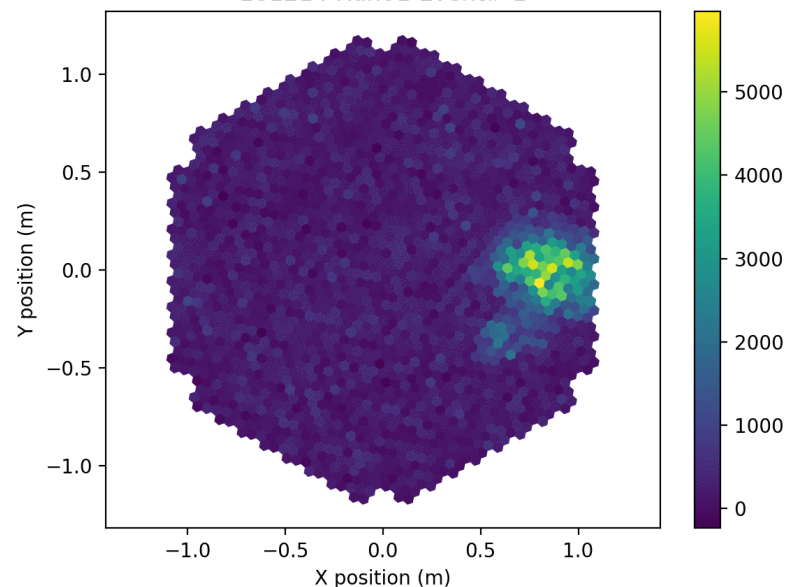
Technological R&D: photosensors, medical imaging and quantum technologies

LHCb detector at LHC (CERN) with the Experimental Particle Physics group



Cherenkov Telescope Array with the High Energy Astrophysics group

181214 Run01 Event# 1



VIRGO gravitational wave detector involves many groups and the 2 sections of the TU

